



SOT1346-1

plastic extremely thin small outline package; no leads; 20 terminals; body 2.00 x 2.70 x 0.40 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	XQFN20
Package type industry code	XQFN20
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	16-5-2013

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.95	-	2	2.05	mm
E	package width		2.65	-	2.7	2.75	mm
A	seated height		[tbd]	-	[tbd]	0.4	mm
e	nominal pitch		-	-	0.4	-	mm
n ₂	actual quantity of termination		-	-	20	-	



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2. Package outline

X2QFN20: plastic extremely thin small outline package; no leads;
20 terminals; body 2.00 x 2.70 x 0.40 mm

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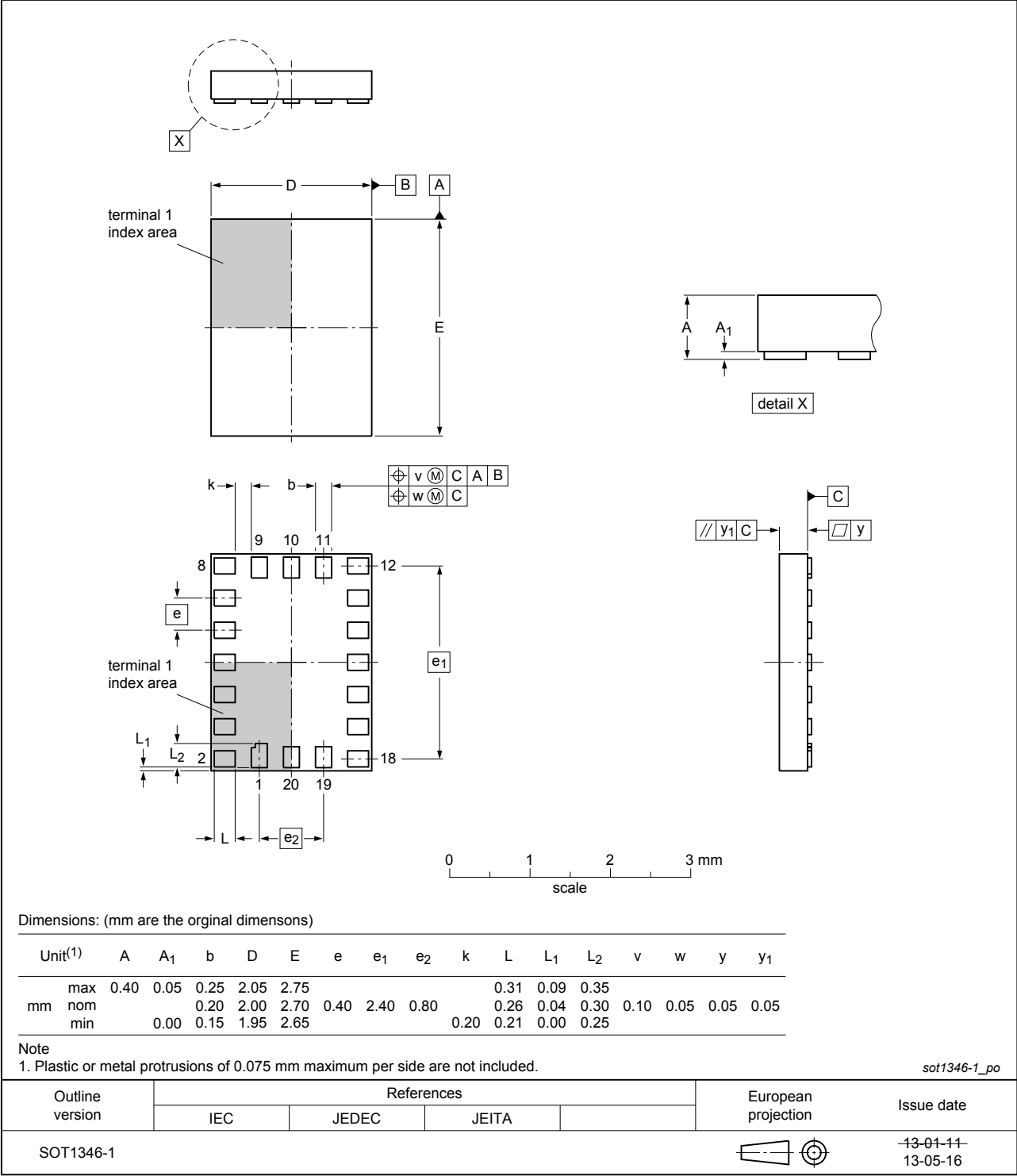


Fig. 1. Package outline XQFN20 (SOT1346-1)

3. Soldering

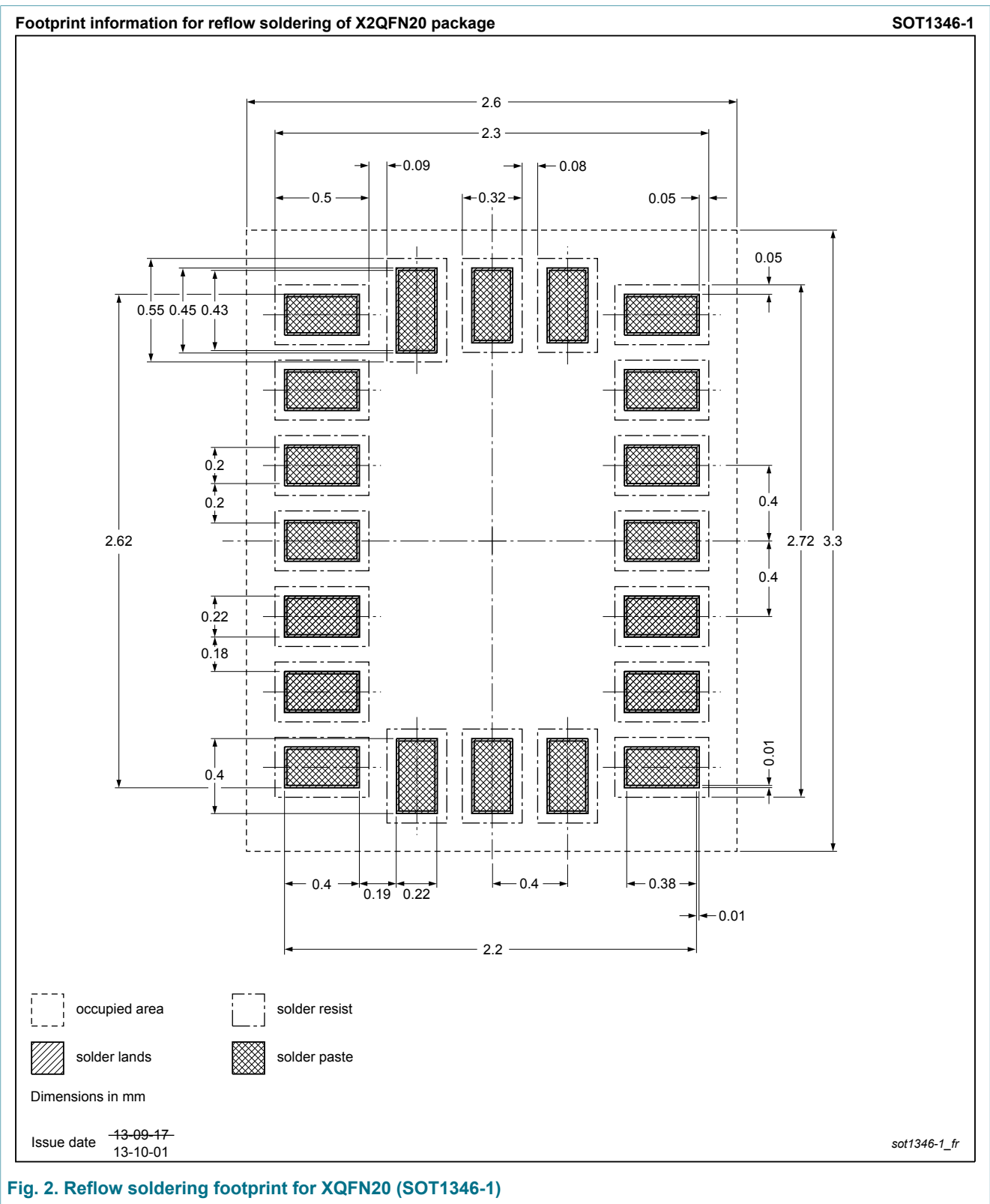


Fig. 2. Reflow soldering footprint for XQFN20 (SOT1346-1)

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4. Legal information

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